

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

SS5150B-MS THRU SS5200B-MS

Product specification


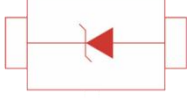
Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O

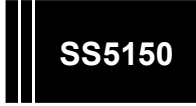

MECHANICAL DATA

- Case: SMB/DO-214AA, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.093 grams (approx.)

Reference News

DO-214AA/SMB	Schematic Diagram
	

Marking

SS5150B-MS	SS5200B-MS
	

Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

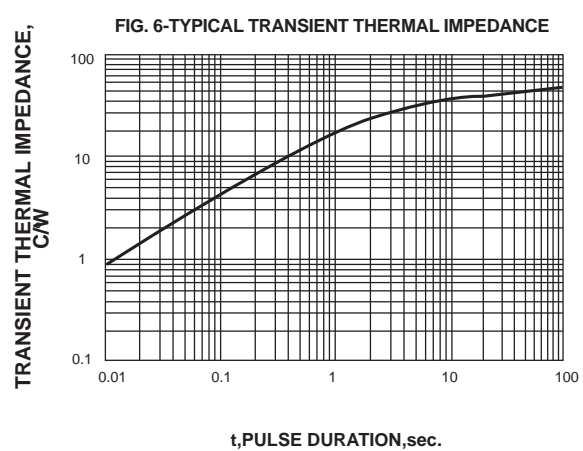
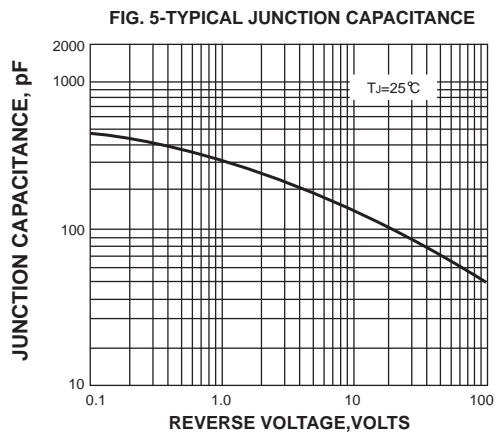
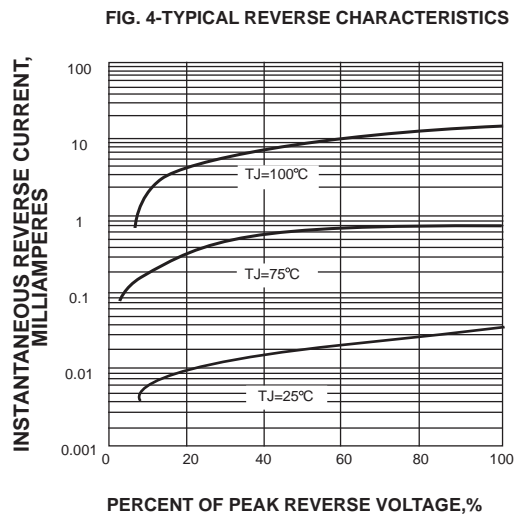
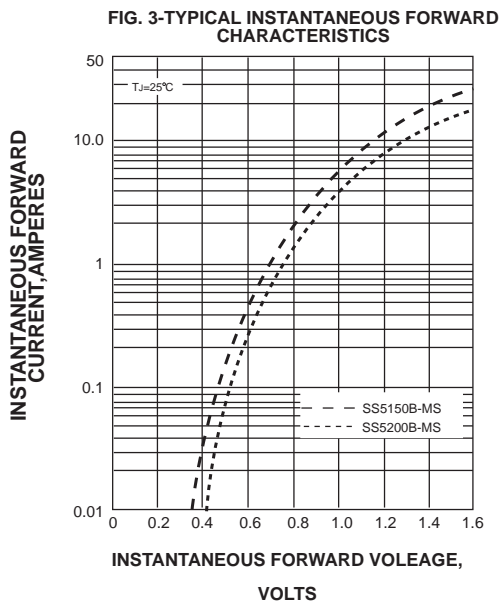
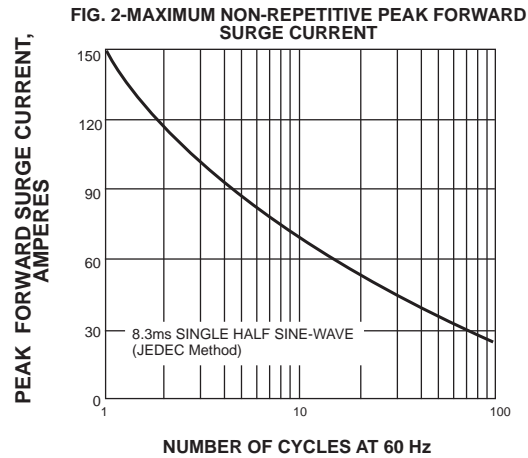
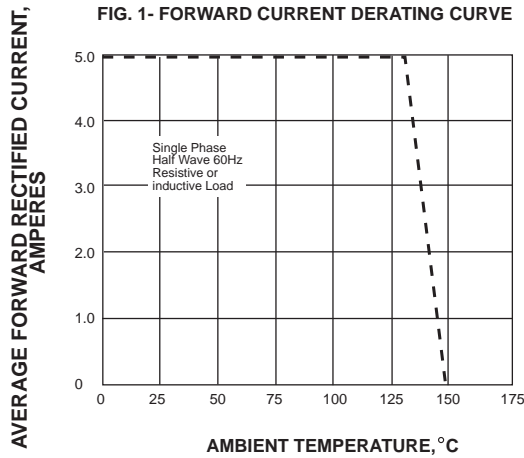
Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	SS5150B-MS	SS5200B-MS	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	150	200	Volts
Maximum RMS voltage	V _{RMS}	105	150	Volts
Maximum DC blocking voltage	V _{DC}	150	200	Volts
Maximum average forward rectified current at T _L (see fig.1)	I _(AV)	5.0		Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	150.0		Amps
Maximum instantaneous forward voltage at 5.0A	V _F	0.85	0.95	Volts
Maximum DC reverse current at rated DC blocking voltage	I _R	0.2		mA
		2.0		
Typical junction capacitance (NOTE 1)	C _J	200		pF
Typical thermal resistance (NOTE 2)	R _{θJA}	50.0		°C/W
Operating junction temperature range	T _J ,	-50 to +150		°C
Storage temperature range	T _{STG}	-50 to +150		°C

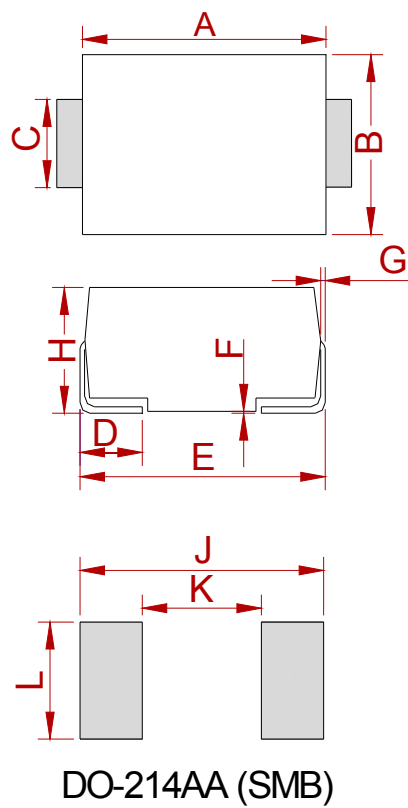
Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

RATINGS AND CHARACTERISTIC CURVES SS5150B-MS THRU SS5200B-MS



PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.75	0.167	0.187
B	3.30	3.94	0.130	0.155
C	1.85	2.21	0.073	0.087
D	0.76	1.52	0.030	0.060
E	5.08	5.59	0.200	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.11	2.44	0.083	0.096
J	6.80		0.270	
K		2.60		0.100
L	2.40		0.090	

REEL SPECIFICATION

P/N	PKG	QTY
SS5150B-MS THRU SS5200B-MS	DO-214AA(SMB)	3000

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